

Maximum 3A, Ultra Low Dropout Regulator

General Description

The RT9018C is a high performance positive voltage regulator designed for use in applications requiring very low input voltage and very low dropout voltage at up to 3A (Peak). It operates with a VIN as low as 1.4V and VDD voltage 3V with output voltage programmable as low as 0.8V. A significant feature includes ultra low dropout, which is ideal for applications where VOUT is very close to VIN. Additionally, there is an enable pin to further reduce power dissipation while shutdown. The RT9018C provides excellent regulation over variations in line, load and temperature. It also provides a power good signal to indicate whether the voltage level of VOUT has reached 90% of its rating value.

The RT9018C is available in SOP-8 (Exposed Pad) and WDFN-10L 3x3 packages with 1V, 1.05V, 1.2V, 1.5V, 1.8V and 2.5V internally preset outputs that are also adjustable using external resistors.

Ordering Information

- RT9018C-□□□
- Package Type
 - SP : SOP-8 (Exposed Pad-Option 1)
 - QW : WDFN-10L 3x3
 - Lead Plating System
 - P : Pb Free
 - G : Green (Halogen Free and Pb Free)
 - Z : ECO (Ecological Element with Halogen Free and Pb free)
 - Output Voltage
 - 10 : 1V/Adj
 - 1K : 1.05V/Adj
 - 12 : 1.2V/Adj
 - 15 : 1.5V/Adj
 - 18 : 1.8V/Adj
 - 25 : 2.5V/Adj

Note :

Richtek products are :

- ▶ RoHS compliant and compatible with the current requirements of IPC/JEDEC J-STD-020.
- ▶ Suitable for use in SnPb or Pb-free soldering processes.

Features

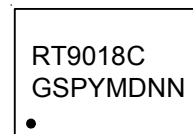
- Maximum 3A Low Dropout Voltage Regulator
- High Accuracy Output Voltage $\pm 1.5\%$
- Typically 210mV Dropout at 3A
- Power Good Output
- Output Voltage Pull Low Resistance when Disable
- Thermal and Over Current Protection
- RoHS Compliant and Halogen Free

Applications

- Front Side Bus VTT (1.2V/3A)
- Notebook PC Applications
- Motherboard Applications

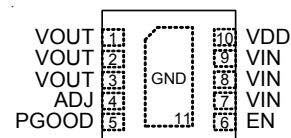
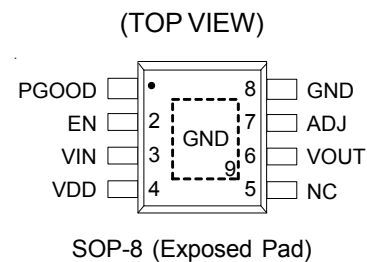
Marking Information

RT9018CGSP



RT9018CGSP : Product Number
YMDNN : Date Code

Pin Configuration



Part Status

Part No	Status	Package Type	Lead plating System
RT9018C-XXGQW	Obsolete	WDFN-10L 3x3	Green (Halogen Free and Pb Free)
RT9018C-XXGSP	Obsolete	SOP-8 (Exposed Pad)	Green (Halogen Free and Pb Free)
RT9018C-XXZQW	Obsolete	WDFN-10L 3x3	ECO (Ecological Element with Halogen Free and Pb free)
RT9018C-XXZSP	Obsolete	SOP-8 (Exposed Pad)	ECO (Ecological Element with Halogen Free and Pb free)

The part status values are defined as follows:

Active: Device is in production and is recommended for new designs.

Lifebuy: The device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs.

Preview: Device has been announced but is not in production.

Obsolete: Richtek has discontinued the production of the device.

Pin Description

Pin No.		Pin Name	Pin Function
SOP-8 (Exposed Pad)	WDFN-10L 3x3		
3	7, 8, 9	VIN	Supply Input Voltage.
2	6	EN	Chip Enable (Active-High).
4	10	VDD	Supply Voltage of Control Circuitry.
1	5	PGOOD	Power Good Open Drain Output.
7	4	ADJ	Set the output voltage by the internal feedback resistors when ADJ is grounded. If external feedback resistors is used, $V_{OUT} = 0.8V \times (R1 + R2) / R2$.
6	1, 2, 3	VOUT	Output Voltage.
5	--	NC	No Internal Connection.
8, 9 (Exposed Pad)	11 (Exposed Pad)	GND	Ground. The exposed pad must be soldered to a large PCB and connected to GND for maximum power dissipation.

Typical Application Circuit

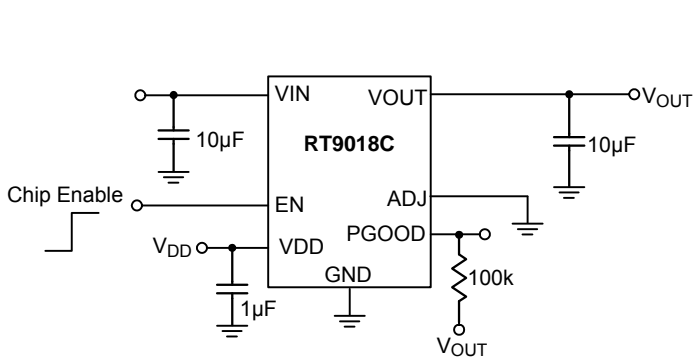


Figure 1. Fixed Voltage Regulator

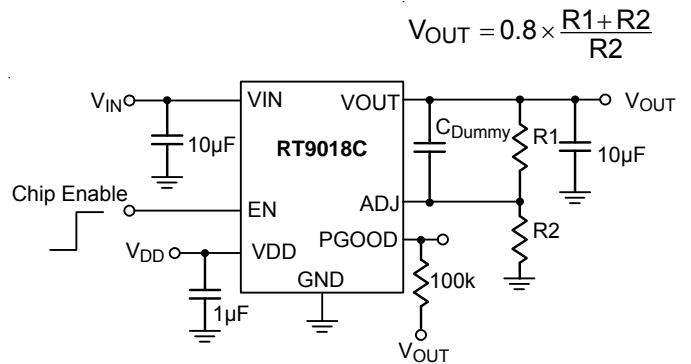
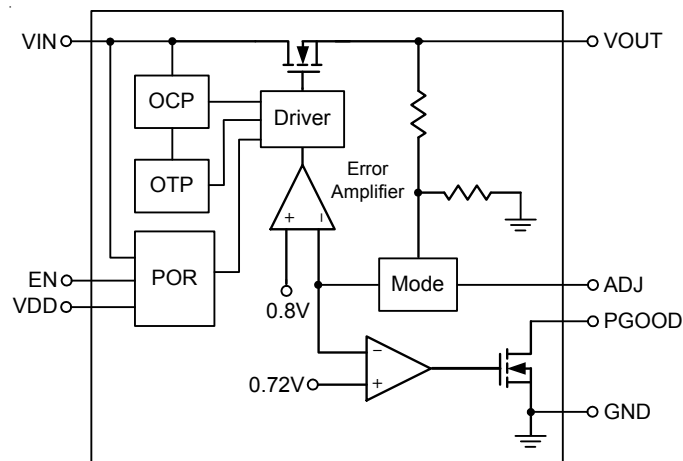


Figure 2. Adjustable Voltage Regulator

Function Block Diagram



Absolute Maximum Ratings (Note 1)

- Supply Voltage, V_{IN} ----- 1V to 6V
- Control Voltage, V_{DD} ----- 3V to 6V
- Output Voltage, V_{OUT} ----- 0.8 to 6V
- Power Dissipation, P_D @ $T_A = 25^\circ\text{C}$
 - SOP-8 (Exposed Pad) ----- 1.33W
 - WDFN-10L 3x3 ----- 1.67W
- Package Thermal Resistance (Note 2)
 - SOP-8 (Exposed Pad), θ_{JA} ----- 75°C/W
 - SOP-8 (Exposed Pad), θ_{JC} ----- 15°C/W
 - WDFN-10L 3x3, θ_{JA} ----- 60°C/W
- Junction Temperature ----- 150°C
- Lead Temperature (Soldering, 10 sec.) ----- 260°C
- Storage Temperature Range ----- -65°C to 150°C
- ESD Susceptibility (Note 3)
 - HBM (Human Body Model) ----- 2kV
 - MM (Machine Model) ----- 200V

Recommended Operating Conditions (Note 4)

- Supply Voltage, V_{IN} ----- 1.4V to 5.5V
- Control Voltage, V_{DD} ($V_{DD} > V_{OUT} + 1.5\text{V}$) ----- 3V to 5.5V
- Control Voltage with PGOOD, V_{DD} (Note 8) ----- 4.5V to 5.5V
- Junction Temperature Range ----- -40°C to 125°C
- Ambient Temperature Range ----- -40°C to 85°C

Electrical Characteristics

($V_{IN} = V_{OUT} + 500\text{mV}$, $V_{EN} = V_{DD} = 5\text{V}$, $C_{IN} = C_{OUT} = 10\mu\text{F}$, $T_A = T_J = 25^\circ\text{C}$, unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
POR Threshold			2.4	2.7	3	V
POR Hysteresis			0.15	0.2	--	V
Adjustable Pin Threshold	V_{TH_ADJ}	$I_{OUT} = 1\text{mA}$	--	0.2	0.4	V
Reference Voltage (ADJ Pin Voltage)	V_{ADJ}	$I_{OUT} = 1\text{mA}$	0.788	0.8	0.812	V
Fixed Output Voltage Range	ΔV_{OUT}		-1.5	0	1.5	%
Line Regulation (V_{IN})	ΔV_{LINE_IN}	$V_{IN} = V_{OUT} + 0.5\text{V}$ to 5V , $I_{OUT} = 1\text{mA}$	--	0.2	0.6	%
Load Regulation (Note 5)	ΔV_{LOAD}	$V_{IN} = V_{OUT} + 1\text{V}$, $I_{OUT} = 1\text{mA}$ to 3A	--	0.2	1	%
Dropout Voltage (Note 6)	V_{DROP}	$I_{OUT} = 2\text{A}$	--	150	250	mV
		$I_{OUT} = 3\text{A}$	--	210	350	mV
Quiescent Current (Note 7)	I_Q	$V_{DD} = 5.5\text{V}$	--	0.6	1.2	mA
Current Limit	I_{LIM}		3.2	4.5	--	A

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Short Circuit Current		$V_{OUT} < 0.2V$	0.5	1.8	--	A
V_{OUT} Pull Low Resistance		$V_{EN} = 0V$	--	150	--	Ω
Chip Enable						
EN Input Bias Current	I_{EN}	$V_{EN} = 0V$	--	12	--	μA
VDD Shutdown Current	I_{SHDN}	$V_{EN} = 0V$	--	--	1	μA
EN Threshold Voltage	Logic-High	V_{ENH}	$V_{DD} = 5V$	1.2	--	V
	Logic-Low	V_{ENL}	$V_{DD} = 5V$	--	0.2	
Power Good						
PGOOD Rising Threshold			--	90	93	%
PGOOD Hysteresis			3	10	--	%
PGOOD Sink Capability		$I_{PGOOD} = 10mA$	--	0.2	0.4	V
PGOOD Delay			0.5	1.5	5	ms
Thermal Protection						
Thermal Shutdown Temperature	T_{SD}		--	160	--	$^{\circ}C$
Thermal Shutdown Hysteresis	ΔT_{SD}		--	30	--	$^{\circ}C$
Thermal Shutdown Temperature Fold-back		$V_{OUT} < 0.4V$	--	110	--	$^{\circ}C$

Note 1. Stresses beyond those listed “Absolute Maximum Ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions may affect device reliability.

Note 2. θ_{JA} is measured at $T_A = 25^{\circ}C$ on a high effective thermal conductivity four-layer test board per JEDEC 51-7. θ_{JC} is measured at the exposed pad of the package.

Note 3. Devices are ESD sensitive. Handling precaution recommended.

Note 4. The device is not guaranteed to function outside its operating conditions.

Note 5. Regulation is measured at constant junction temperature by using a 2ms current pulse. Devices are tested for load regulation in the load range from 1mA to 3A.

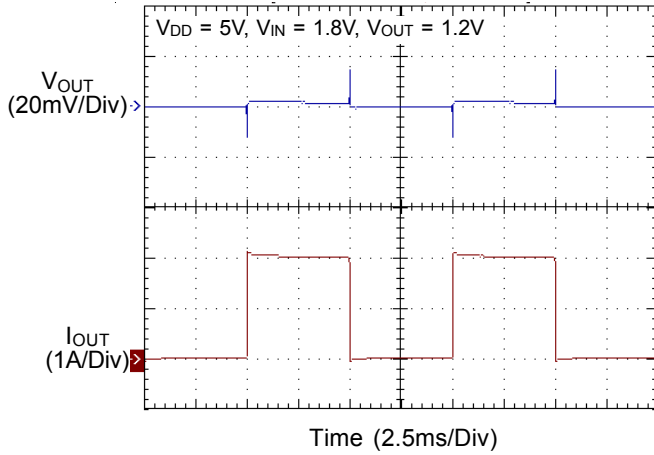
Note 6. The dropout voltage is defined as $V_{IN} - V_{OUT}$, which is measured when V_{OUT} is $V_{OUT(NORMAL)} - 100mV$.

Note 7. Quiescent, or ground current, is the difference between input and output currents. It is defined by $I_Q = I_{IN} - I_{OUT}$ under no load condition ($I_{OUT} = 0mA$). The total current drawn from the supply is the sum of the load current plus the ground pin current.

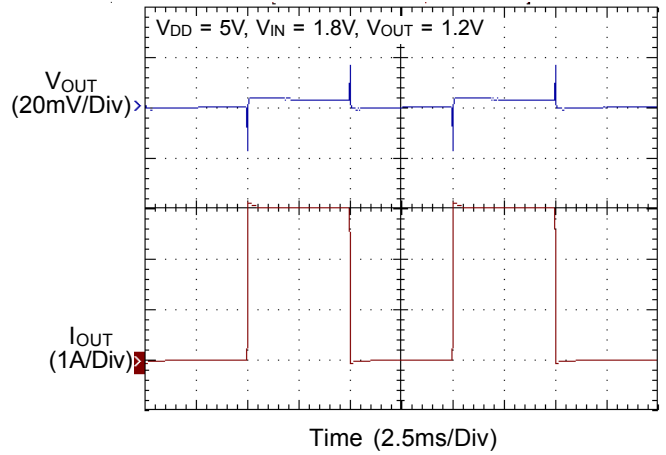
Note 8. The control voltage must within 4.5V to 5.5V when using PGOOD function.

Typical Operating Characteristics

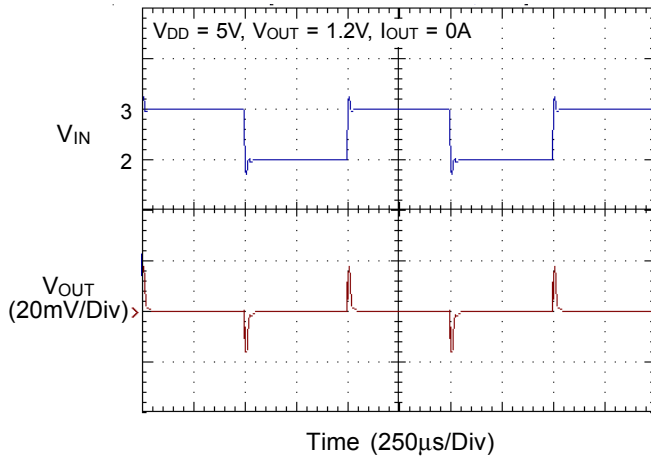
Load Transient Response



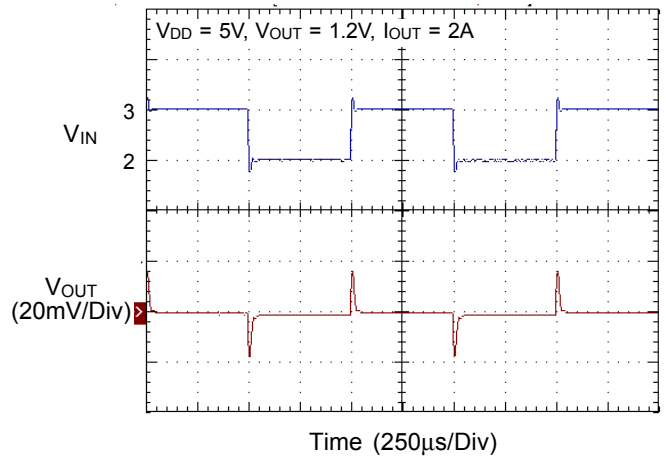
Load Transient Response



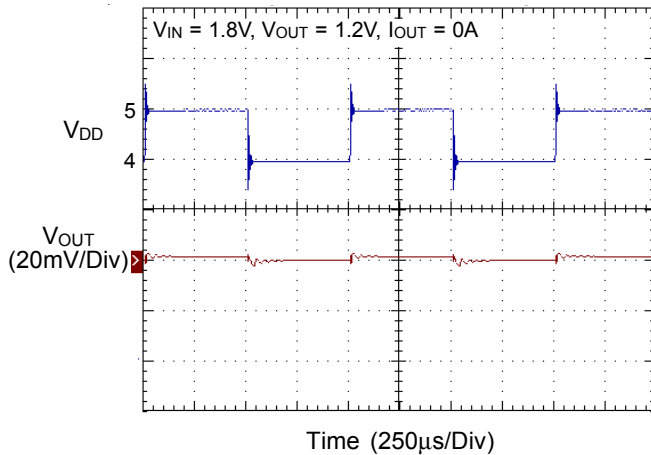
V_{IN} Line Transient Response



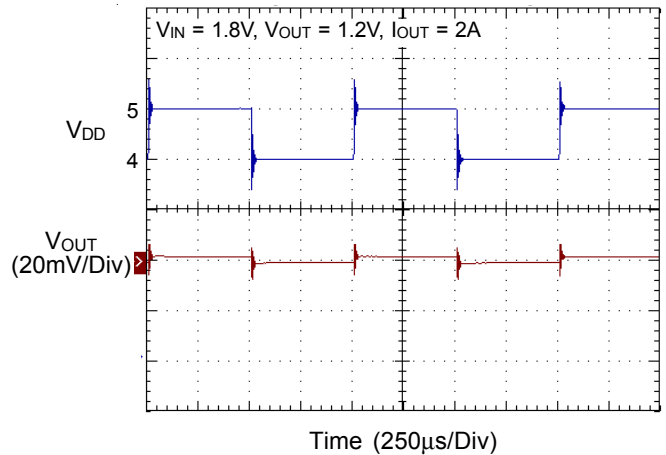
V_{IN} Line Transient Response



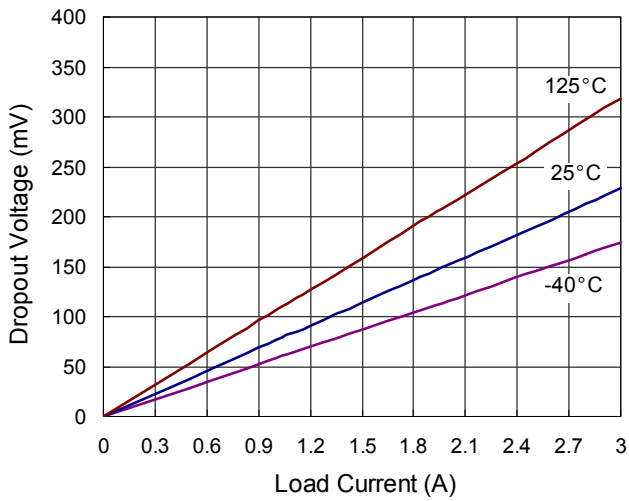
V_{DD} Line Transient Response



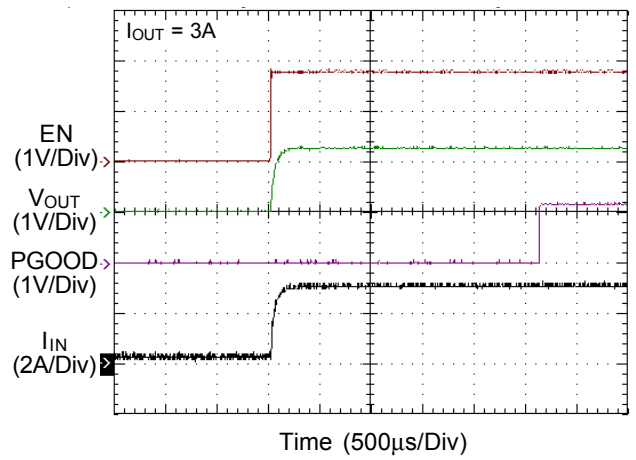
V_{DD} Line Transient Response



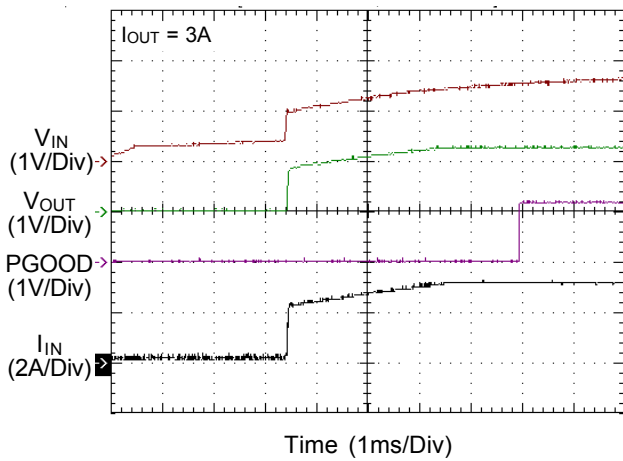
Dropout Voltage vs. Load Current



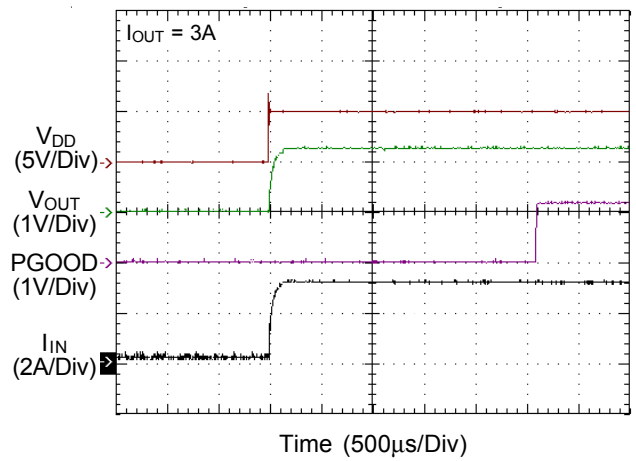
Start Up from EN



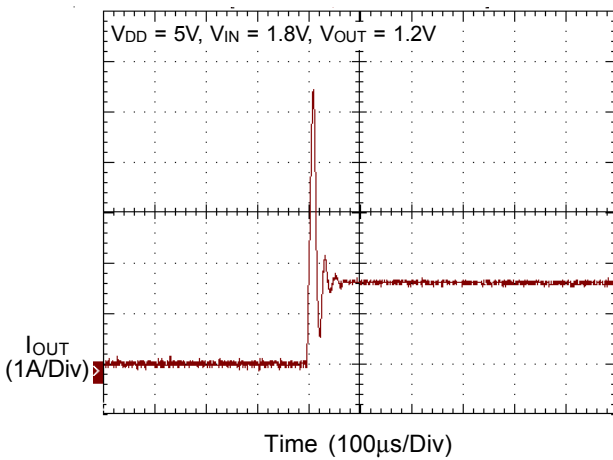
Start Up from V_{IN}



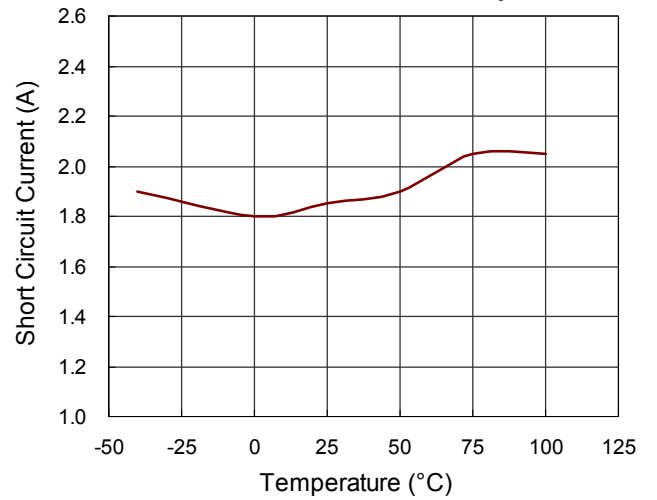
Start Up from V_{DD}



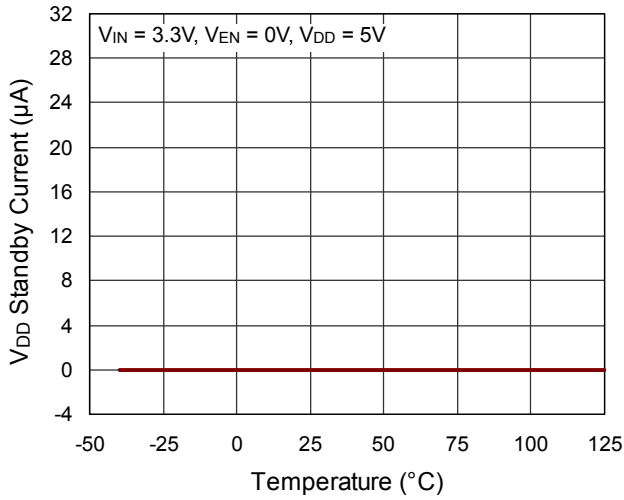
Short Circuit Protection



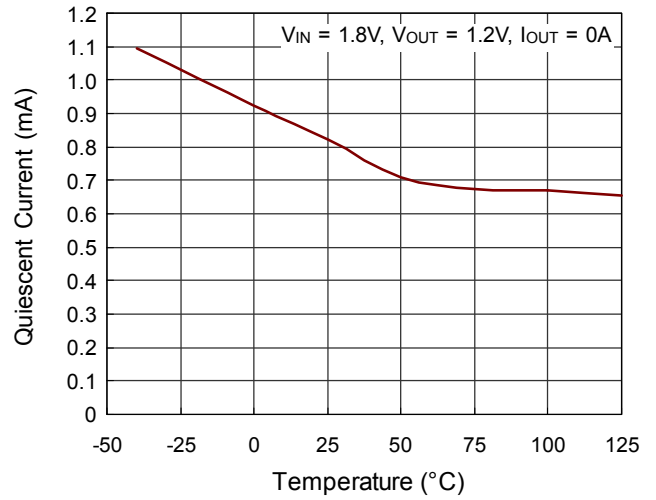
Short Circuit Current vs. Temperature



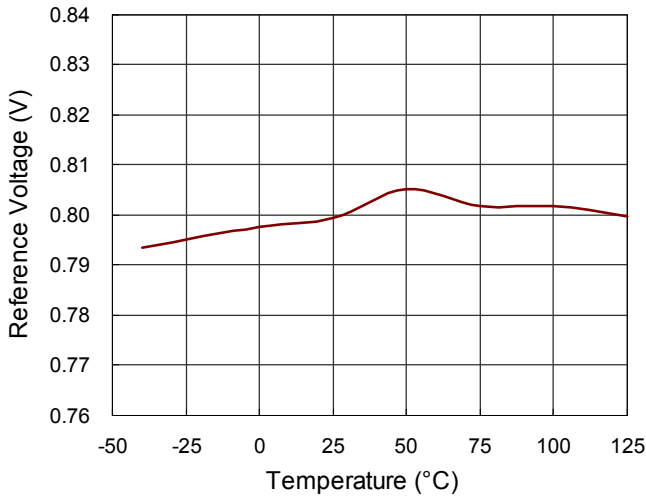
V_{DD} Standby Current vs. Temperature



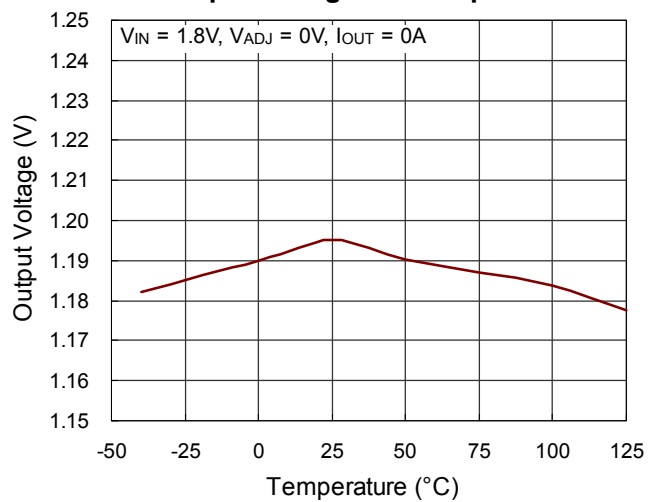
Quiescent Current vs. Temperature



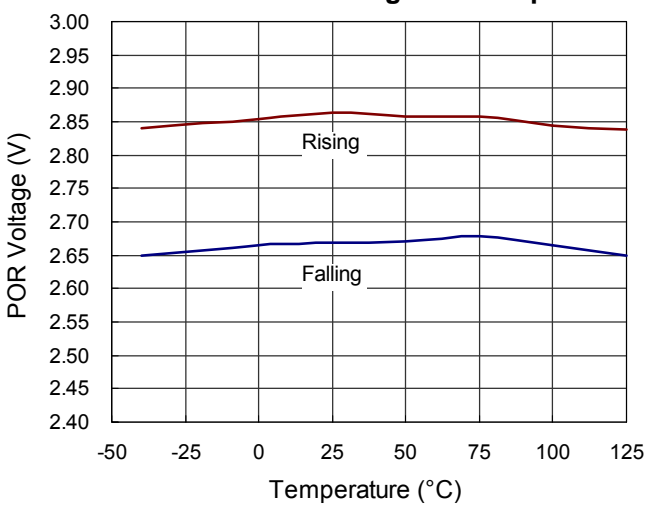
Reference Voltage vs. Temperature



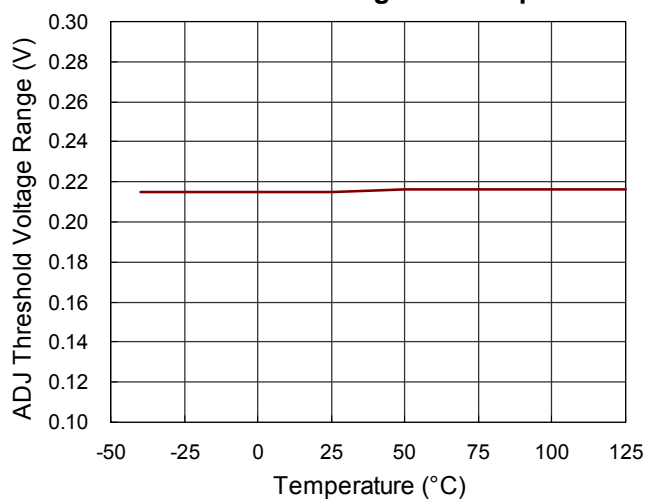
Output Voltage vs. Temperature

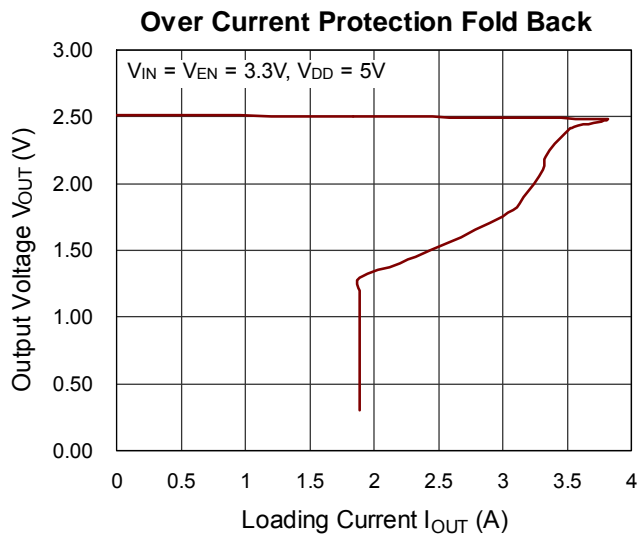


V_{DD} POR Threshold Voltage vs. Temperature



ADJ Threshold Voltage vs. Temperature





Application Information

Adjustable Mode Operation

The output voltage of the RT9018C is adjustable from 0.8V to $(V_{IN} - V_{DROP})$ via external voltage divider resistors as shown in Typical Application Circuit (Figure 2). The value of resistors, R1 and R2, should be more than 10kΩ to reduce the power loss. V_{DD} must be greater than $(V_{OUT} + 1.5V)$.

Enable

The RT9018C goes into shutdown mode when the EN pin is in the logic low condition. During this condition, the pass transistor, error amplifier, and band gap are turned off, reducing the supply current to 10μA typically. The RT9018C goes into operation mode when the EN pin is in the logic high condition. Note that if the EN pin is floating, the EN pin function pulls low level internally. Thus, the regulator will be turned off when EN pin is floating.

Output Capacitor

The RT9018C is specifically designed to employ ceramic output capacitors as low as 10μF. The ceramic capacitors offer significant cost and space savings, along with high frequency noise filtering.

Input Capacitor

Good bypassing is recommended from input to ground to help improve AC performance. A 10μF input capacitor or greater located as close as possible to the IC is recommended.

Current Limit

The RT9018C contains an independent current limit and short circuit current protection to prevent unexpected applications. The current limit monitors and controls the pass transistor's gate voltage, limiting the output current to higher than 4.5A typically. When the output voltage is less than 0.4V, the short circuit current protection starts the current fold back function and maintains the loading current at 1.8A. The output can be shorted to ground indefinitely without damaging the part.

Power Good

The power good function is an open-drain output. Connect a 100kΩ pull up resistor to VOUT to obtain an output voltage. The PGOOD pin will output high immediately after the output voltage arrives 90% of normal output voltage. The PGOOD pin will output high with a typical 1.5ms delay time.

Thermal Shutdown Protection

Thermal protection limits power dissipation to prevent IC over temperature in the RT9018C. When the operation junction temperature exceeds 160°C, the over-temperature protection circuit starts the thermal shutdown function and turns the pass transistor off. The pass transistor turn on again after the junction temperature cools by 30°C. RT9018C lowers its OTP trip level from 160°C to 110°C when output short circuit occurs ($V_{OUT} < 0.4V$). It limits IC case temperature under 100°C and provides maximum safety to customer while output short circuit occurs.

Power Dissipation

For continuous operation, do not exceed absolute maximum operation junction temperature 125°C. The power dissipation definition in device is :

$$P_D = (V_{IN} - V_{OUT}) \times I_{OUT} + V_{IN} \times I_Q$$

The maximum power dissipation depends on the thermal resistance of IC package, PCB layout, the rate of surroundings airflow and temperature difference between junctions to ambient. The maximum power dissipation can be calculated by following formula :

$$P_{D(MAX)} = (T_{J(MAX)} - T_A) / \theta_{JA}$$

where $T_{J(MAX)}$ is the maximum operation junction temperature 125°C, T_A is the ambient temperature and the θ_{JA} is the junction to ambient thermal resistance.

For recommended operating conditions specification, where $T_{J(MAX)}$ is the maximum junction temperature of the die (125°C) and T_A is the maximum ambient temperature. The junction to ambient thermal resistance for SOP-8 (Exposed Pad) package is 75°C/W on the standard JEDEC 51-7 (4 layers, 2S2P) thermal test board. The copper thickness is 2oz. The maximum power dissipation at $T_A =$

25°C can be calculated by following formula :

$$P_{D (MAX)} = (125^{\circ}\text{C} - 25^{\circ}\text{C}) / (75^{\circ}\text{C/W}) = 1.33\text{W}$$

(SOP-8 Exposed Pad on the minimum layout)

Layout Considerations

The thermal resistance θ_{JA} of SOP-8 (Exposed Pad) is determined by the package design and the PCB design. However, the package design had been designed. If possible, it's useful to increase thermal performance by the PCB design. The thermal resistance θ_{JA} can be decreased by adding a copper under the exposed pad of SOP-8 (Exposed Pad) package.

As shown in Figure 3, the amount of copper area to which the SOP-8 (Exposed Pad) is mounted affects thermal performance. When mounted to the standard SOP-8 (Exposed Pad) pad (Figure 3.a), θ_{JA} is 75°C/W. Adding copper area of pad under the SOP-8 (Exposed Pad) Figure 3.b) reduces the θ_{JA} to 64°C/W. Even further, increasing the copper area of pad to 70mm² (Figure 3.e) reduces the θ_{JA} to 49°C/W.

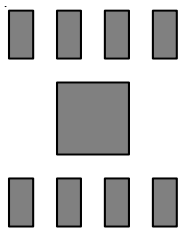


Figure 3 (a). Minimum Footprint, $\theta_{JA} = 75^{\circ}\text{C/W}$

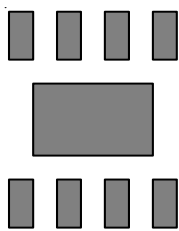


Figure 3 (b). Copper Area = 10mm², $\theta_{JA} = 64^{\circ}\text{C/W}$

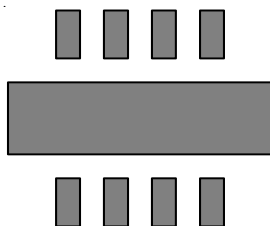


Figure 3 (c). Copper Area = 30mm², $\theta_{JA} = 54^{\circ}\text{C/W}$

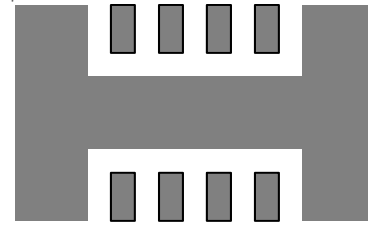


Figure 3 (d). Copper Area = 50mm², $\theta_{JA} = 51^{\circ}\text{C/W}$

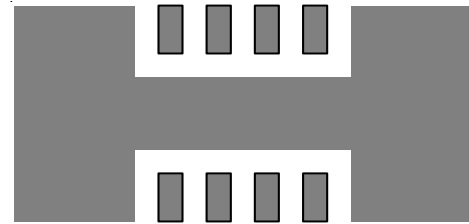


Figure 3 (e). Copper Area = 70mm², $\theta_{JA} = 49^{\circ}\text{C/W}$

Figure 3. Thermal Resistance vs. Different Cooper Area Layout Design

The maximum power dissipation depends on operating ambient temperature for fixed $T_{J(MAX)}$ and thermal resistance θ_{JA} . The Figure 4 of de-rating curves allows the designer to see the effect of rising ambient temperature on the maximum power allowed.

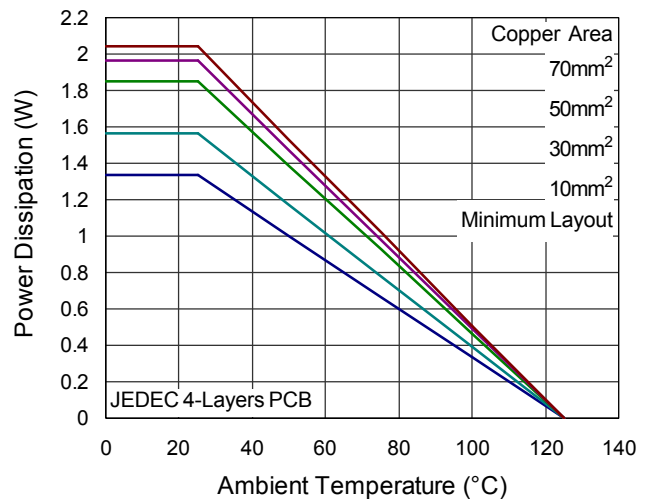
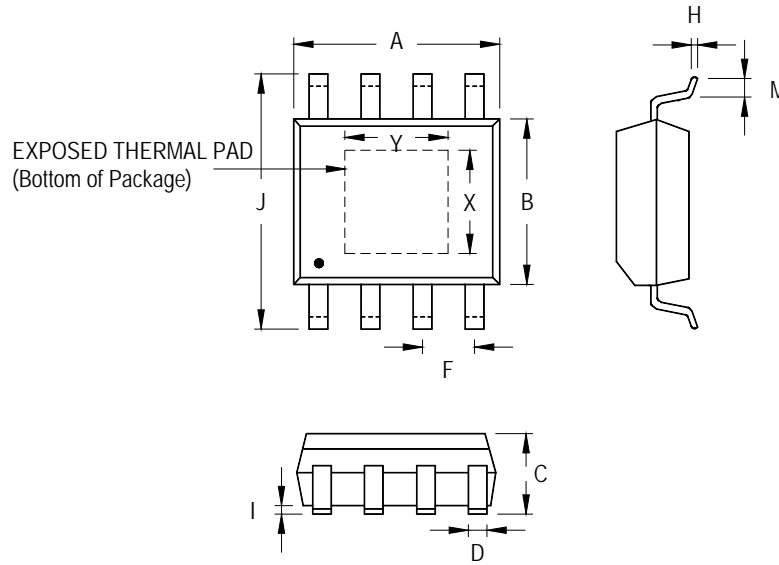


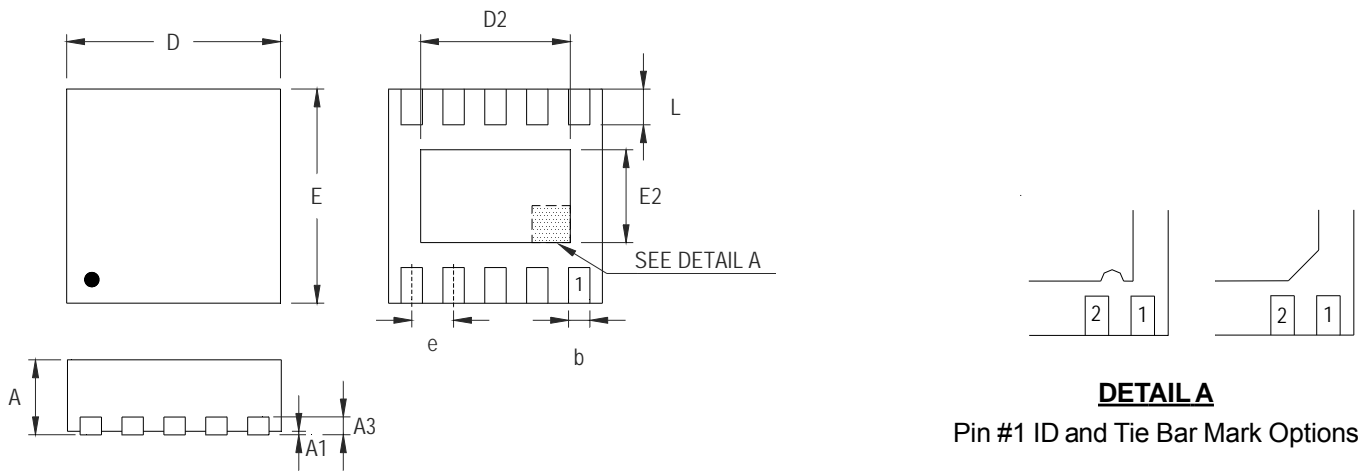
Figure 4. De-rating Curves

Outline Dimension



Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min	Max	Min	Max	
A	4.801	5.004	0.189	0.197	
B	3.810	4.000	0.150	0.157	
C	1.346	1.753	0.053	0.069	
D	0.330	0.510	0.013	0.020	
F	1.194	1.346	0.047	0.053	
H	0.170	0.254	0.007	0.010	
I	0.000	0.152	0.000	0.006	
J	5.791	6.200	0.228	0.244	
M	0.406	1.270	0.016	0.050	
Option 1	X	2.000	2.300	0.079	0.091
	Y	2.000	2.300	0.079	0.091
Option 2	X	2.100	2.500	0.083	0.098
	Y	3.000	3.500	0.118	0.138

8-Lead SOP (Exposed Pad) Plastic Package



DETAIL A
Pin #1 ID and Tie Bar Mark Options

Note : The configuration of the Pin #1 identifier is optional, but must be located within the zone indicated.

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.700	0.800	0.028	0.031
A1	0.000	0.050	0.000	0.002
A3	0.175	0.250	0.007	0.010
b	0.180	0.300	0.007	0.012
D	2.950	3.050	0.116	0.120
D2	2.300	2.650	0.091	0.104
E	2.950	3.050	0.116	0.120
E2	1.500	1.750	0.059	0.069
e	0.500		0.020	
L	0.350	0.450	0.014	0.018

W-Type 10L DFN 3x3 Package

Richtek Technology Corporation

14F, No. 8, Tai Yuen 1st Street, Chupei City
Hsinchu, Taiwan, R.O.C.
Tel: (8863)5526789



Richtek products are sold by description only. Richtek reserves the right to change the circuitry and/or specifications without notice at any time. Customers should obtain the latest relevant information and data sheets before placing orders and should verify that such information is current and complete. Richtek cannot assume responsibility for use of any circuitry other than circuitry entirely embodied in a Richtek product. Information furnished by Richtek is believed to be accurate and reliable. However, no responsibility is assumed by Richtek or its subsidiaries for its use; nor for any infringements of patents or other rights of third parties which may result from its use. No license is granted by implication or otherwise under any patent or patent rights of Richtek or its subsidiaries.